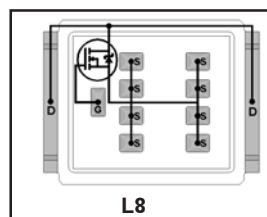


Automotive DirectFET™ Power MOSFET ②

- Advanced Process Technology
- Optimized for Automotive Motor Drive, DC-DC and other Heavy Load Applications
- Exceptionally Small Footprint and Low Profile
- High Power Density
- Low Parasitic Parameters
- Dual Sided Cooling
- 175°C Operating Temperature
- Repetitive Avalanche Capability for Robustness and Reliability
- Lead free, RoHS and Halogen free

$V_{(BR)DSS}$	40V
$R_{DS(on)}$ typ.	700 $\mu\Omega$
max.	1000 $\mu\Omega$
I_D (Silicon Limited)	270A
Q_g	220nC



Applicable DirectFET Outline and Substrate Outline ①

SB	SC			M2	M4		L4	L6	L8	
----	----	--	--	----	----	--	----	----	----	--

Description

The AUIRF7739L2TR(1) combines the latest Automotive HEXFET® Power MOSFET Silicon technology with the advanced DirectFET™ packaging to achieve the lowest on-state resistance in a package that has the footprint of a DPak (TO-252AA) and only 0.7 mm profile. The DirectFET package is compatible with existing layout geometries used in power applications, PCB assembly equipment and vapor phase, infra-red or convection soldering techniques, when application note AN-1035 is followed regarding the manufacturing methods and processes. The DirectFET package allows dual sided cooling to maximize thermal transfer in automotive power systems.

This HEXFET® Power MOSFET is designed for applications where efficiency and power density are essential. The advanced DirectFET packaging platform coupled with the latest silicon technology allows the AUIRF7739L2TR(1) to offer substantial system level savings and performance improvement specifically in motor drive, high frequency DC-DC and other heavy load applications on ICE, HEV and EV platforms. This MOSFET utilizes the latest processing techniques to achieve low on-resistance and low Q_g per silicon area. Additional features of this MOSFET are 175°C operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for high current automotive applications.

Absolute Maximum Ratings

	Parameter	Max.	Units
V _{DS}	Drain-to-Source Voltage	40	V
V _{GS}	Gate-to-Source Voltage	± 20	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)④	270	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)④	190	
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)③	46	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Package Limited)	375	
I _{DM}	Pulsed Drain Current ④	1070	
P _D @T _C = 25°C	Power Dissipation ④	125	W
P _D @T _A = 25°C	Power Dissipation ③	3.8	
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited) ⑥	270	mJ
E _{AS} (tested)	Single Pulse Avalanche Energy Tested Value ⑤	160	
I _{AR}	Avalanche Current ①	See Fig.12a, 12b, 15, 16	A
E _{AR}	Repetitive Avalanche Energy ①		mJ
T _P	Peak Soldering Temperature	270	°C
T _J	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ③	—	40	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient ③	12.5	—	
$R_{\theta JA}$	Junction-to-Ambient ⑨	20	—	
$R_{\theta JCan}$	Junction-to-Can ④⑩	—	1.2	
$R_{\theta J-PCB}$	Junction-to-PCB Mounted	—	0.5	
	Linear Derating Factor ④	0.83		W/ $^\circ\text{C}$

HEXFET® is a registered trademark of International Rectifier.

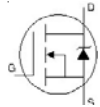
Static Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

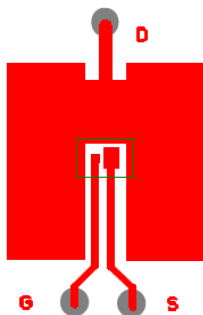
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.008	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1mA$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	700	1000	$\mu\Omega$	$V_{GS} = 10V, I_D = 160A$ ②
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.8	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-6.7	—	mV/ $^\circ\text{C}$	
g_{fs}	Forward Transconductance	290	—	—	S	$V_{DS} = 50V, I_D = 160A$
R_G	Gate Resistance	—	1.5	—	Ω	
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 40V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 40V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$

Dynamic Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

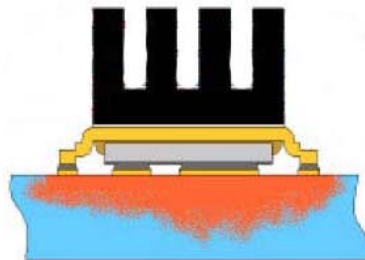
	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge	—	220	330	nC	$V_{DS} = 20V, V_{GS} = 10V$ $I_D = 160A$ See Fig. 11
Q_{gs1}	Pre-V _{th} Gate-to-Source Charge	—	46	—		
Q_{gs2}	Post-V _{th} Gate-to-Source Charge	—	19	—		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	81	—		
Q_{godr}	Gate Charge Overdrive	—	74	—		
Q_{sw}	Switch Charge ($Q_{gs2} + Q_{gd}$)	—	100	—	nC	
Q_{oss}	Output Charge	—	83	—	nC	$V_{DS} = 16V, V_{GS} = 0V$
$t_{d(on)}$	Turn-On Delay Time	—	21	—	ns	$V_{DD} = 20V, V_{GS} = 10V$ ② $I_D = 160A$ $R_G = 1.8\Omega$
t_r	Rise Time	—	71	—		
$t_{d(off)}$	Turn-Off Delay Time	—	56	—		
t_f	Fall Time	—	42	—		
C_{iss}	Input Capacitance	—	11880	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	2510	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	1240	—		$f = 1.0MHz$
C_{oss}	Output Capacitance	—	8610	—		$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
C_{oss}	Output Capacitance	—	2230	—		$V_{GS} = 0V, V_{DS} = 32V, f = 1.0MHz$
$C_{oss \text{ eff.}}$	Effective Output Capacitance	—	3040	—		$V_{GS} = 0V, V_{DS} = 0V \text{ to } 32V$

Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

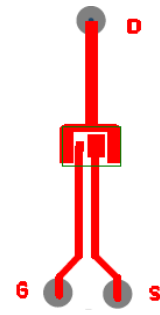
	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	110	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ⑤	—	—	1070		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$I_S = 160A, V_{GS} = 0V$ ②
t_{rr}	Reverse Recovery Time	—	87	130	ns	$I_F = 160A, V_{DD} = 20V$
Q_{rr}	Reverse Recovery Charge	—	250	380	nC	$di/dt = 100A/\mu s$ ②



③ Surface mounted on 1 in. square Cu (still air).



⑨ Mounted to a PCB with small clip heatsink (still air)



⑩ Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)

Notes ① through ⑩ are on page 10

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		DFET2	MSL1
ESD	Machine Model	Class B AEC-Q101-002	
	Human Body Model	Class 2 AEC-Q101-001	
	Charged Device Model	Class IV AEC-Q101-005	
RoHS Compliant		Yes	

† Qualification standards can be found at International Rectifier's web site: <http://www.irf.com>

†† Exceptions to AEC-Q101 requirements are noted in the qualification report.

AUIRF7739L2TR/TR1

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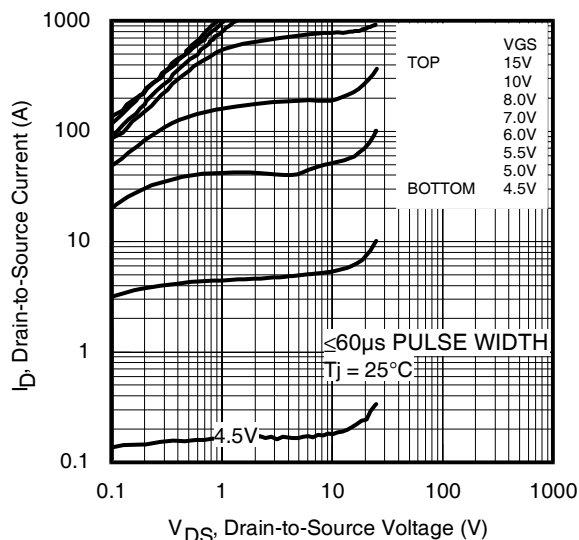


Fig 1. Typical Output Characteristics

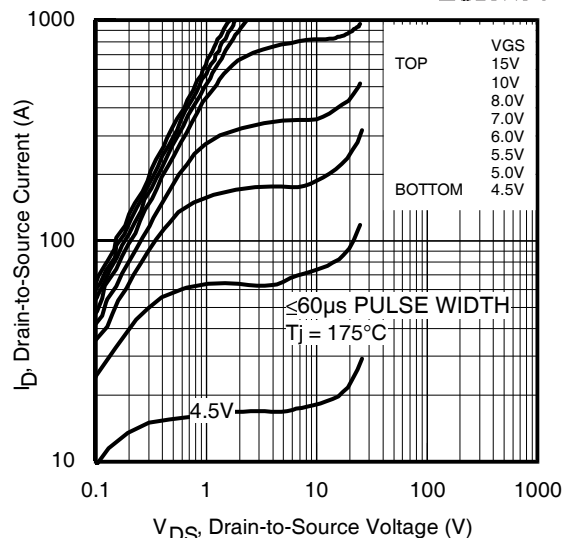


Fig 2. Typical Output Characteristics

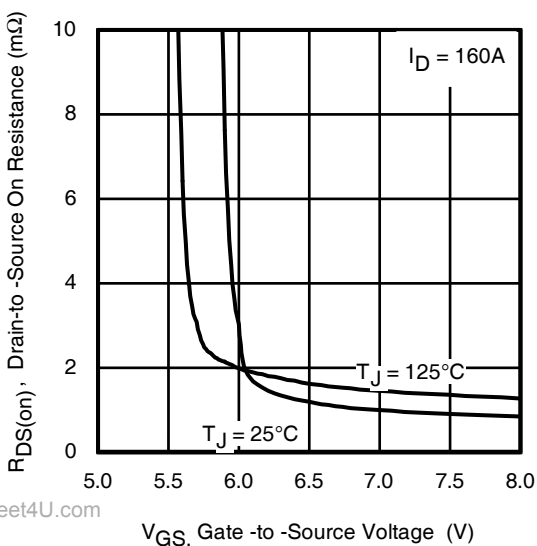


Fig 3. Typical On-Resistance vs. Gate Voltage

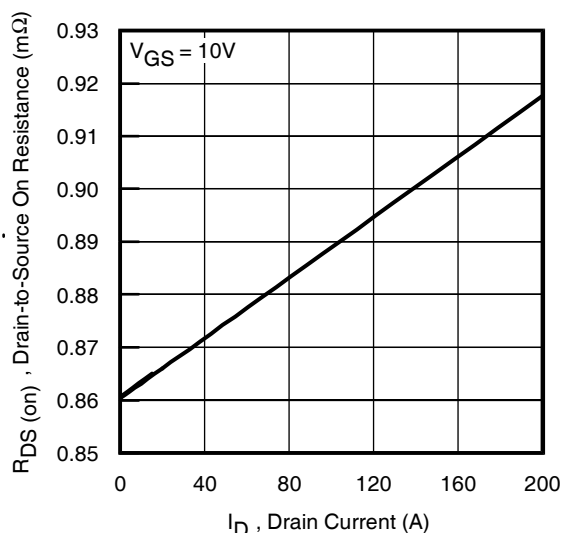


Fig 4. Typical On-Resistance vs. Drain Current

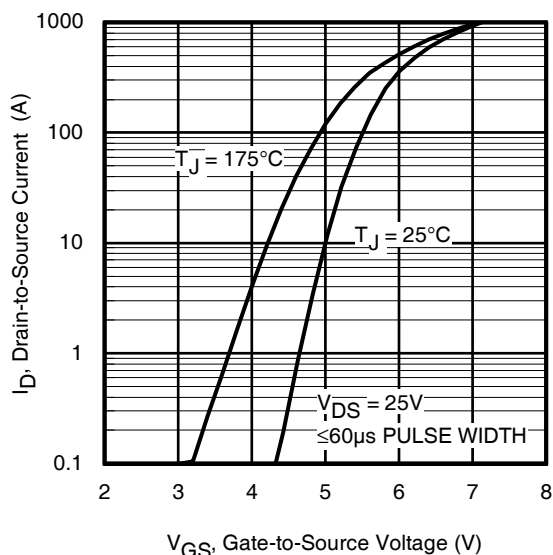


Fig 5. Typical Transfer Characteristics

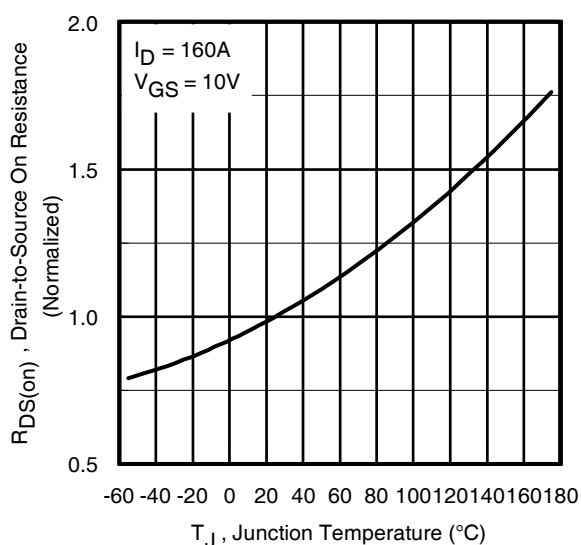


Fig 6. Normalized On-Resistance vs. Temperature

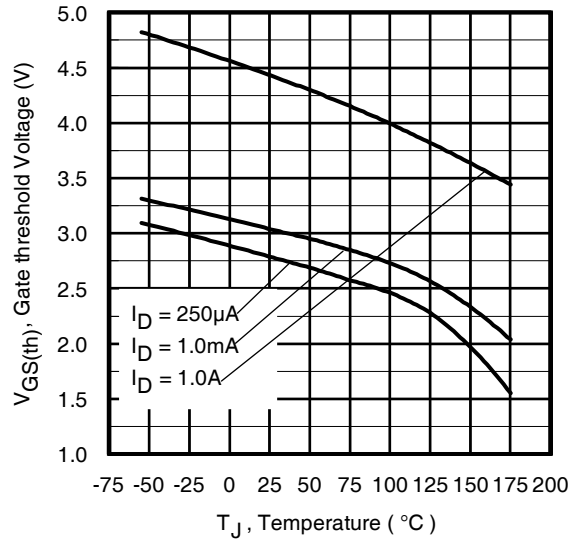


Fig 7. Typical Threshold Voltage vs. Junction Temperature

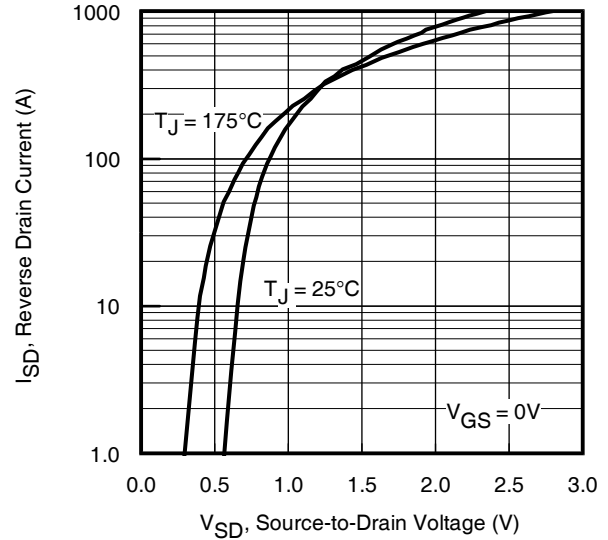


Fig 8. Typical Source-Drain Diode Forward Voltage

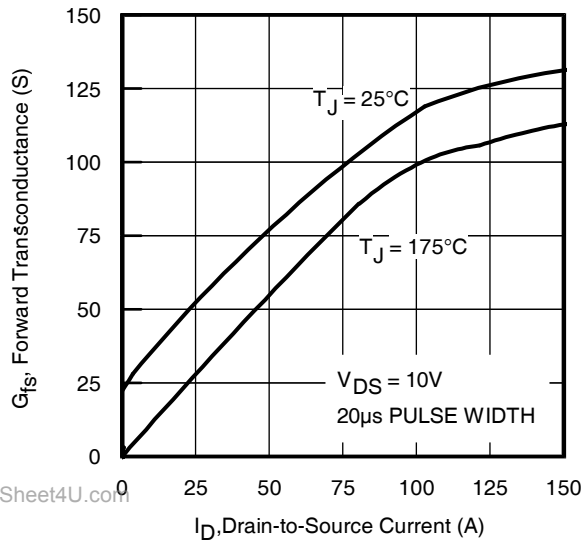


Fig 9. Typical Forward Transconductance vs. Drain Current

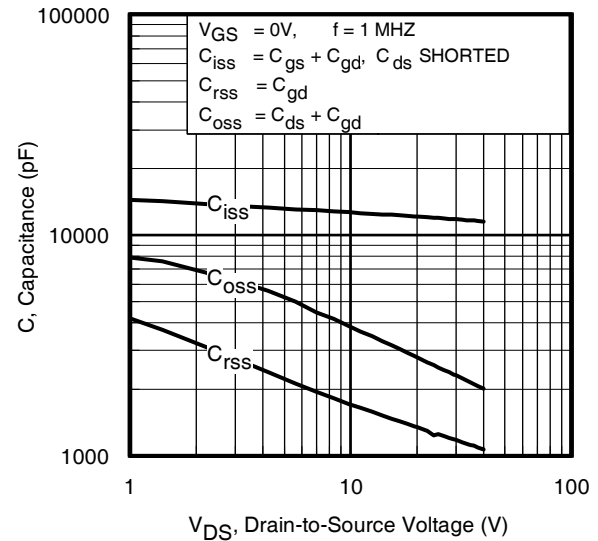


Fig 10. Typical Capacitance vs. Drain-to-Source Voltage

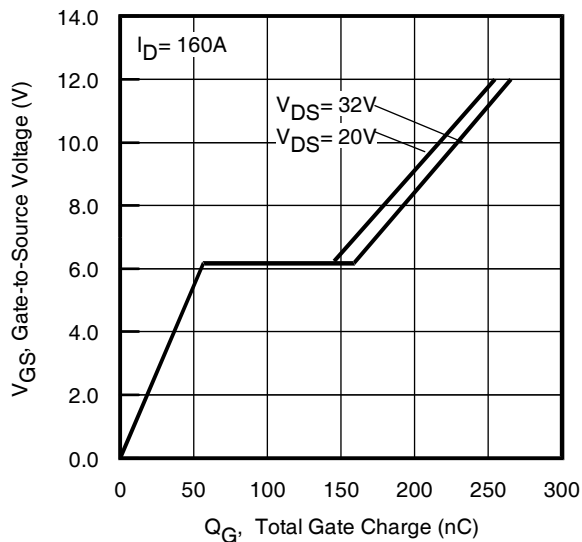


Fig.11 Typical Gate Charge vs. Gate-to-Source Voltage

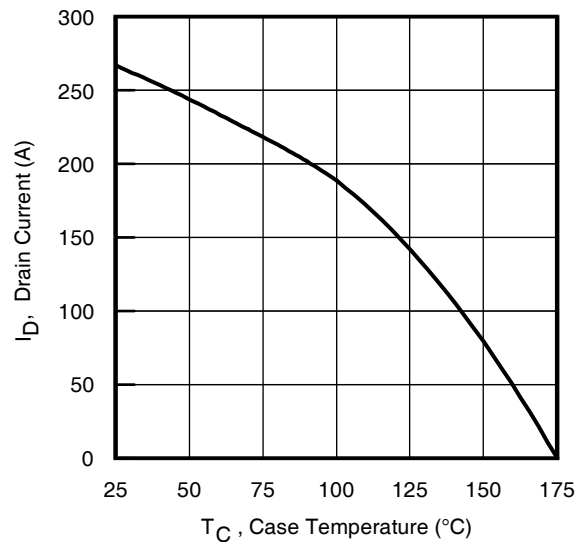


Fig 12. Maximum Drain Current vs. Case Temperature

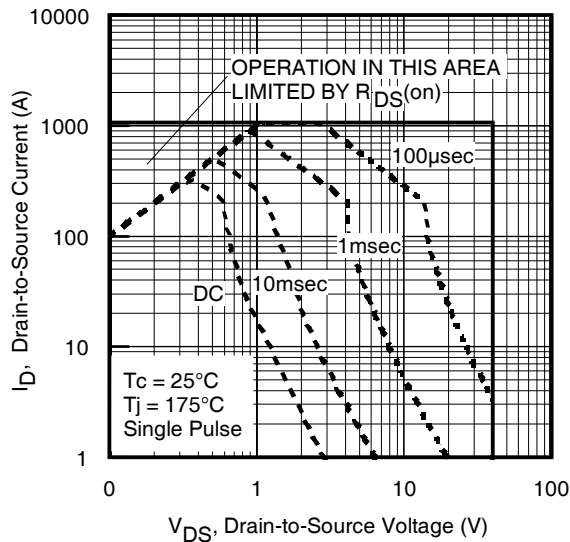


Fig 13. Maximum Safe Operating Area

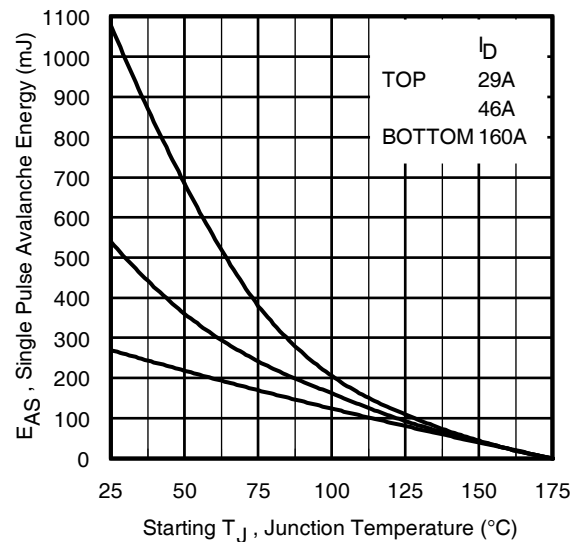


Fig 14. Maximum Avalanche Energy vs. Temperature

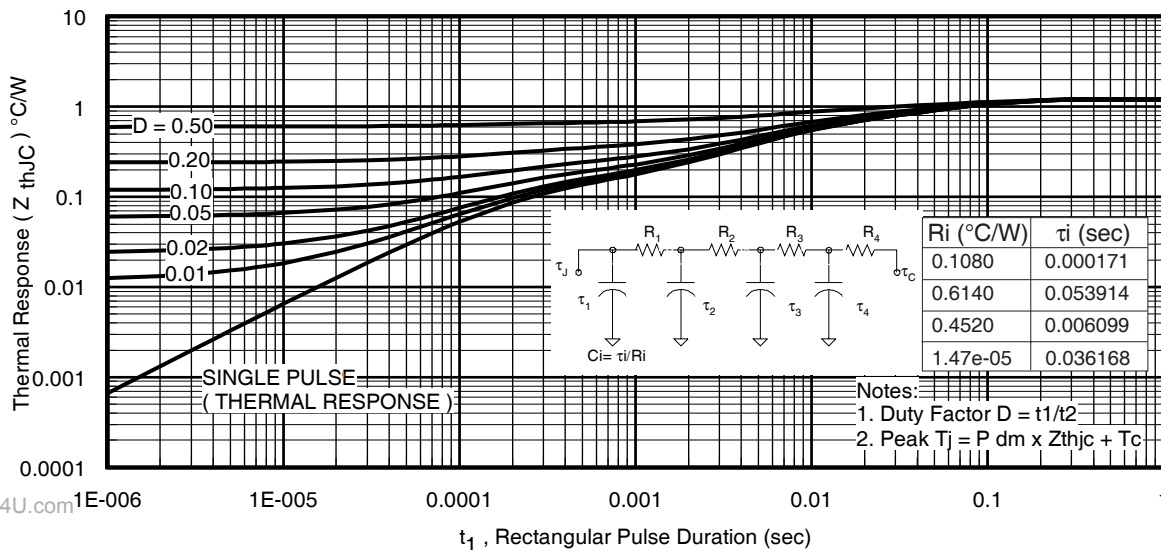


Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

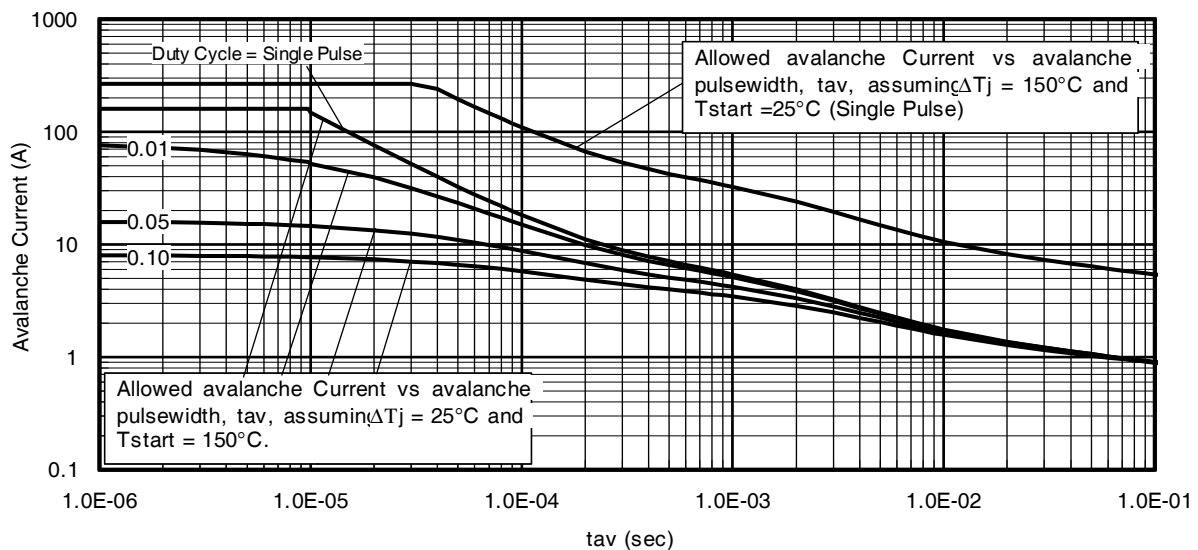


Fig 16. Typical Avalanche Current vs. Pulsewidth

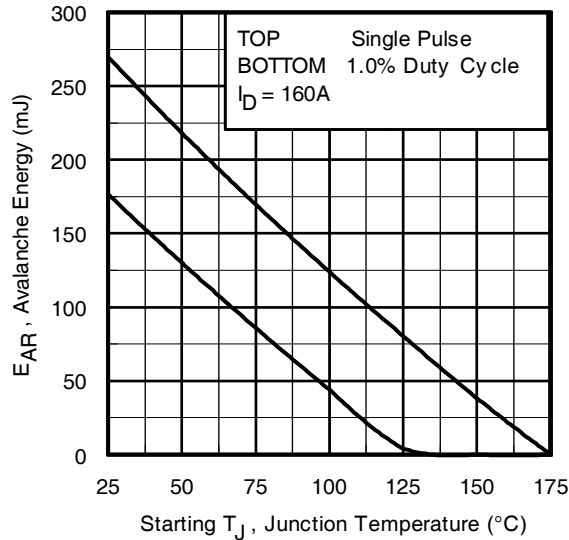


Fig 17. Maximum Avalanche Energy vs. Temperature

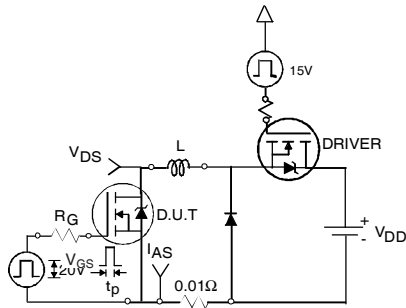


Fig 18a. Unclamped Inductive Test Circuit

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$

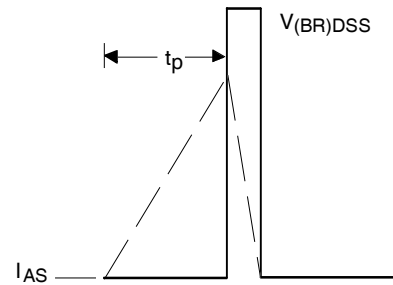


Fig 18b. Unclamped Inductive Waveforms

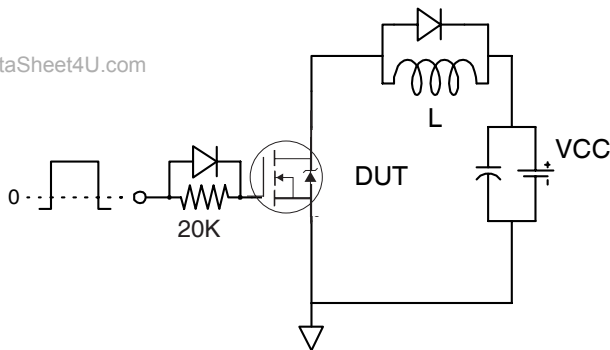


Fig 19a. Gate Charge Test Circuit

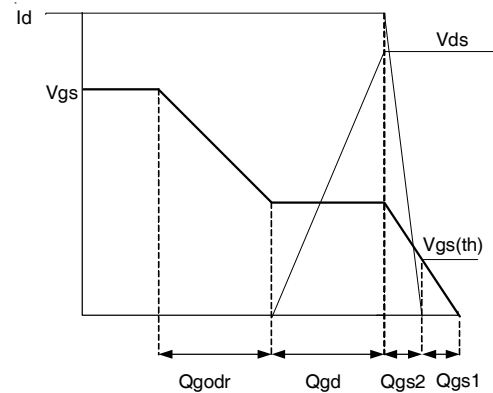


Fig 19b. Gate Charge Waveform

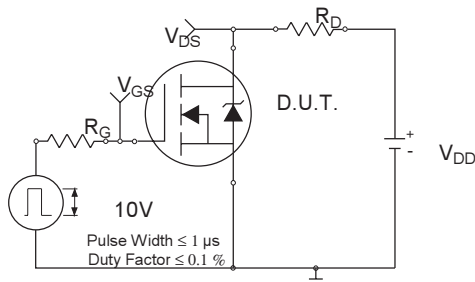


Fig 20a. Switching Time Test Circuit

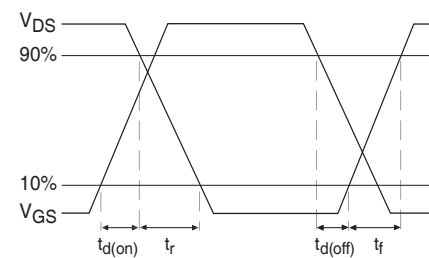


Fig 20b. Switching Time Waveforms

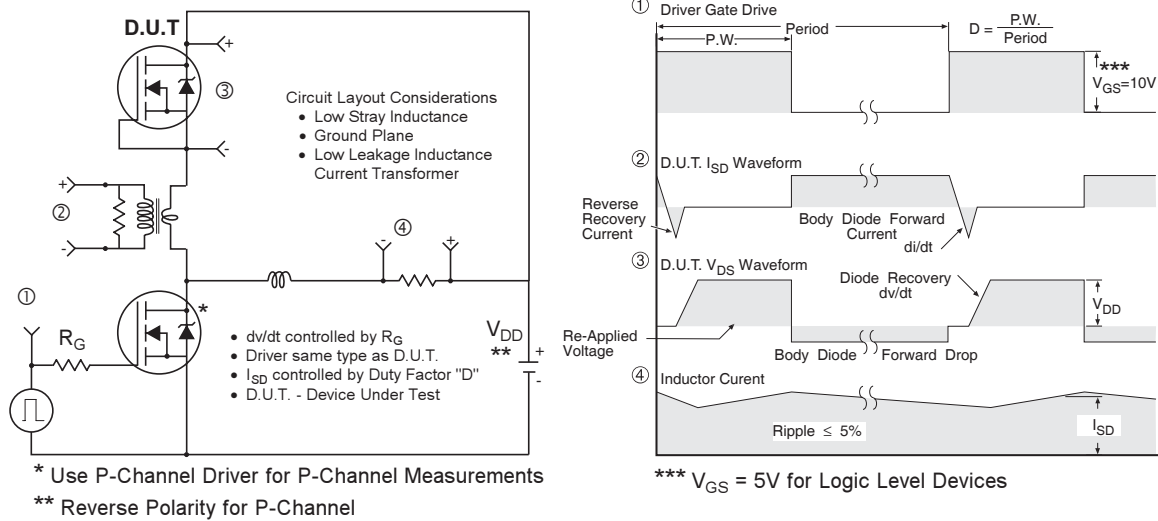
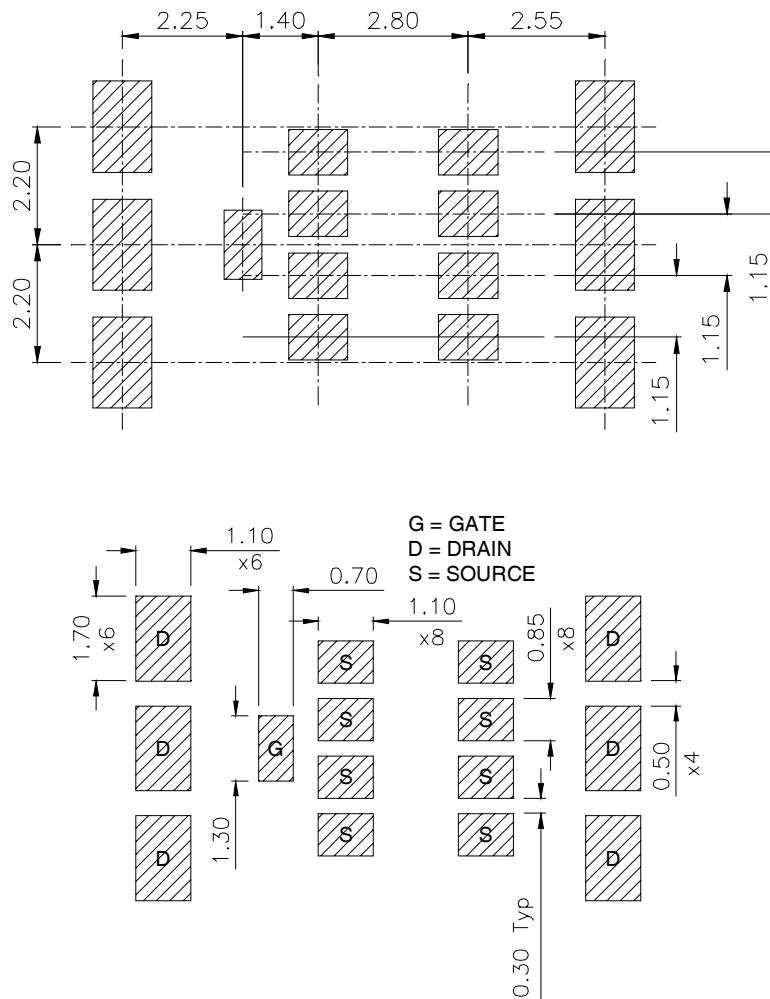


Fig 21. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

Automotive DirectFET™ Board Footprint, L8 (Large Size Can).

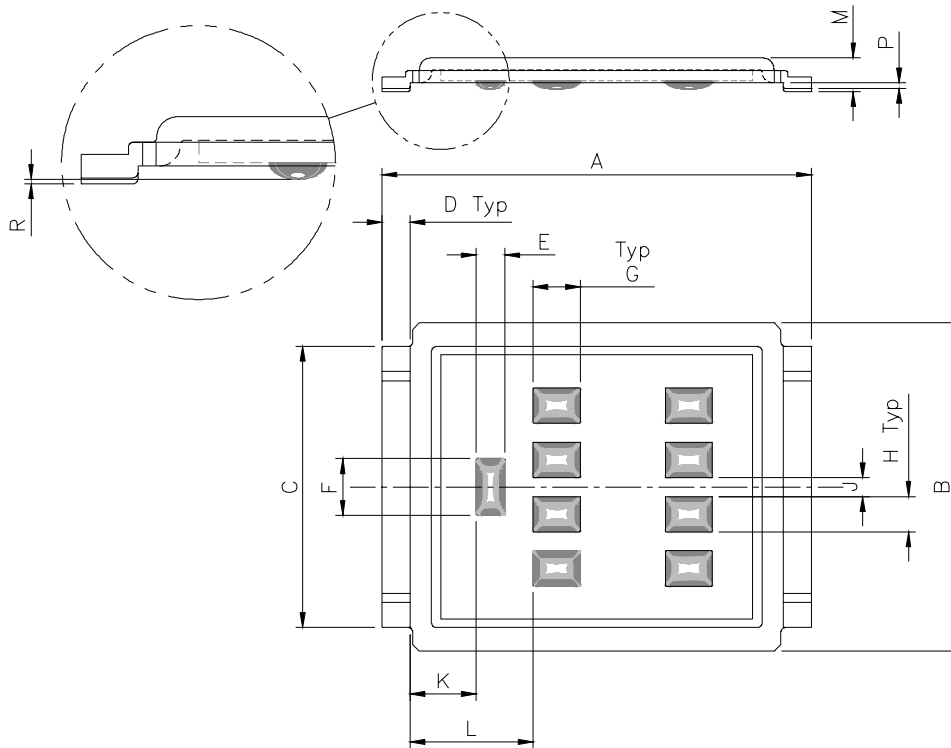
Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

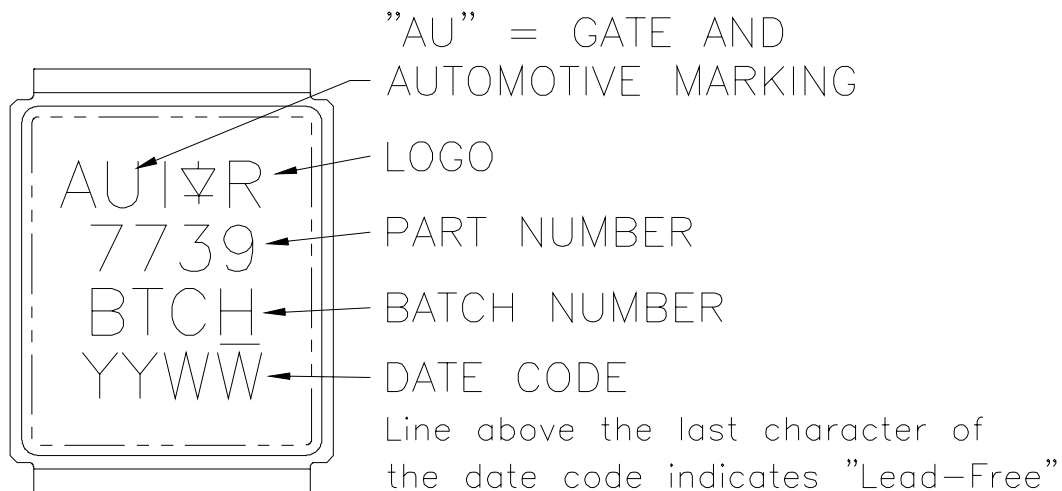
Automotive DirectFET™ Outline Dimension, L8 Outline (LargeSize Can).

Please see AN-1035 for DirectFET assembly details and stencil and substrate design recommendations



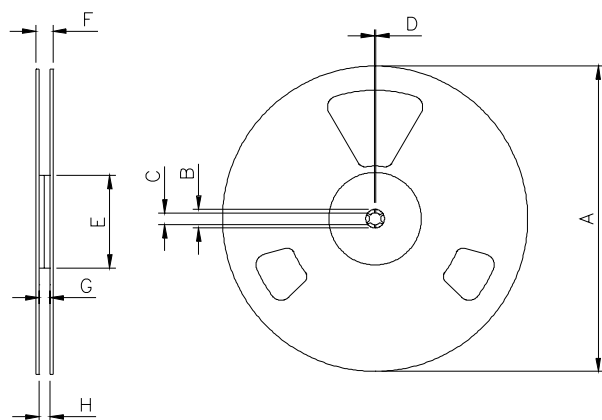
DIMENSIONS				
	METRIC		IMPERIAL	
CODE	MIN	MAX	MIN	MAX
A	9.05	9.15	0.356	0.360
B	6.85	7.10	0.270	0.280
C	5.90	6.00	0.232	0.236
D	0.55	0.65	0.022	0.026
E	0.58	0.62	0.023	0.024
F	1.18	1.22	0.046	0.048
G	0.98	1.02	0.039	0.040
H	0.73	0.77	0.029	0.030
J	0.38	0.42	0.015	0.017
K	1.35	1.45	0.053	0.057
L	2.55	2.65	0.100	0.104
M	0.68	0.74	0.027	0.029
P	0.09	0.17	0.003	0.007
R	0.02	0.08	0.001	0.003

Automotive DirectFET™ Part Marking



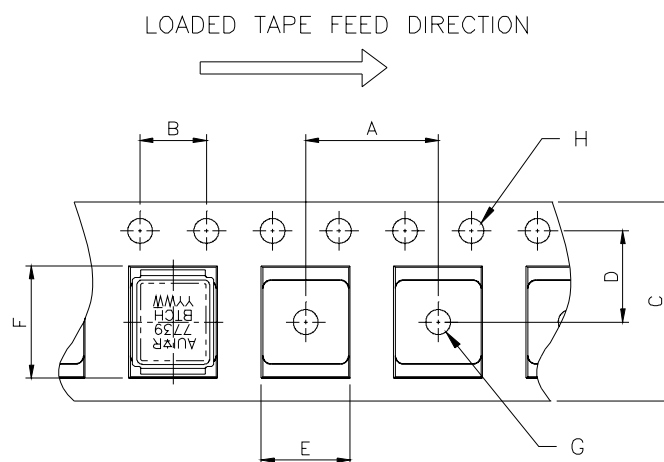
Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

Automotive DirectFET™ Tape & Reel Dimension (Showing component orientation).



NOTE: Controlling dimensions in mm
Std reel quantity is 4000 parts. (ordered as AUIRF7739L2TR). For 1000 parts on 7" reel, order AUIRF7739L2TR1

REEL DIMENSIONS								
STANDARD OPTION (QTY 4000)					TR1 OPTION (QTY 1000)			
CODE	METRIC		IMPERIAL		METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
A	330.00	N.C	12.992	N.C	177.80	N.C	7.000	N.C
B	20.20	N.C	0.795	N.C	20.20	N.C	0.795	N.C
C	12.80	13.20	0.504	0.520	12.98	13.50	0.331	0.50
D	1.50	N.C	0.059	N.C	1.50	2.50	0.059	N.C
E	99.00	100.00	3.900	3.940	62.48	N.C	2.460	N.C
F	N.C	22.40	N.C	0.880	N.C	N.C	N.C	0.53
G	16.40	18.40	0.650	0.720	N.C	N.C	N.C	N.C
H	15.90	19.40	0.630	0.760	16.00	N.C	0.630	N.C



NOTE: CONTROLLING DIMENSIONS IN MM

DIMENSIONS				
CODE	METRIC		IMPERIAL	
	MIN	MAX	MIN	MAX
A	11.90	12.10	4.69	0.476
B	3.90	4.10	0.154	0.161
C	15.90	16.30	0.623	0.642
D	7.40	7.60	0.291	0.299
E	7.20	7.40	0.283	0.291
F	9.90	10.10	0.390	0.398
G	1.50	N.C	0.059	N.C
H	1.50	1.60	0.059	0.063

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

Notes:

- Click on this section to link to the appropriate technical paper.
- Click on this section to link to the DirectFET Website.
- Surface mounted on 1 in. square Cu board, steady state.
- T_C measured with thermocouple mounted to top (Drain) of part.
- Repetitive rating; pulse width limited by max. junction temperature.
- Starting $T_J = 25^\circ\text{C}$, $L = 0.021\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 160\text{A}$.
- Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- Used double sided cooling, mounting pad with large heatsink.
- Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- R_θ is measured at T_J of approximately 90°C .

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IR products are neither designed nor intended for use in automotive applications or environments unless the specific IR products are designated by IR as compliant with ISO/TS 16949 requirements and bear a part number including the designation “AU”. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, IR will not be responsible for any failure to meet such requirements.

For technical support, please contact IR’s Technical Assistance Center
<http://www.irf.com/technical-info/>

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